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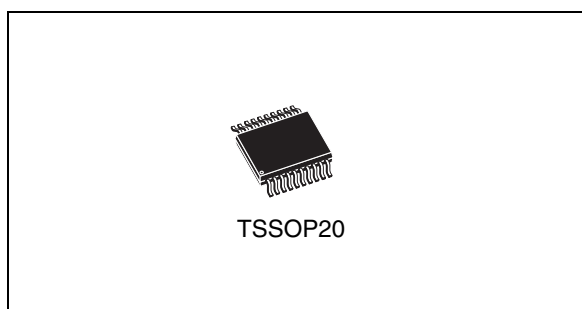


Value Line, 8-bit ultralow power MCU, 8-KB Flash, 256-byte data EEPROM, RTC, timers, USART, I2C, SPI, ADC

Datasheet –production data

Features

- Operating conditions
 - Operating power supply: 1.8 V to 3.6 V
 - Temperature range: -40 °C to 85 °C
- Low power features
 - 5 low power modes: Wait, Low power run (5.1 μ A), Low power wait (3 μ A), Active-halt with RTC (1.3 μ A), Halt (350 nA)
 - Ultra-low leakage per I/O: 50 nA
 - Fast wakeup from Halt: 5 μ s
- Advanced STM8 core
 - Harvard architecture and 3-stage pipeline
 - Max freq: 16 MHz, 16 CISC MIPS peak
 - Up to 40 external interrupt sources
- Reset and supply management
 - Low power, ultra-safe BOR reset with 5 selectable thresholds
 - Ultra low power POR/PDR
 - Programmable voltage detector (PVD)
- Clock management
 - 32 kHz and 1 to 16 MHz crystal oscillators
 - Internal 16 MHz factory-trimmed RC
 - Internal 38 kHz low consumption RC
 - Clock security system
- Low power RTC
 - BCD calendar with alarm interrupt
 - Digital calibration with +/- 0.5 ppm accuracy
 - LSE security system
 - Auto-wakeup from Halt w/ periodic interrupt
- Memories
 - 8 Kbytes of Flash program memory and 256 bytes of data EEPROM with ECC
 - Flexible write and read protection modes
 - 1 Kbyte of RAM



- DMA
 - 4 channels supporting ADC, SPI, I2C, USART, timers
 - 1 channel for memory-to-memory
- 12-bit ADC up to 1 Msps/28 channels
 - Internal reference voltage
- Timers
 - Two 16-bit timers with 2 channels (used as IC, OC, PWM), quadrature encoder
 - One 8-bit timer with 7-bit prescaler
 - 2 watchdogs: 1 Window, 1 Independent
 - Beeper timer with 1, 2 or 4 kHz frequencies
- Communication interfaces
 - Synchronous serial interface (SPI)
 - Fast I²C 400 kHz SMBus and PMBus
 - USART
- Up to 18 I/Os, all mappable on interrupt vectors
- Development support
 - Fast on-chip programming and non-intrusive debugging with SWIM
 - Bootloader using USART

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1 Introduction

This document describes the features, pinout, mechanical data and ordering information for the low density value line STM8L051F3 microcontroller with 8-Kbyte Flash memory density.

For further details on the whole STMicroelectronics low density family please refer to [Section 2.2: Ultra low power continuum](#).

For detailed information on device operation and registers, refer to the reference manual (RM0031).

For information on to the Flash program memory and data EEPROM, refer to the programming manual (PM0054).

For information on the debug module and SWIM (single wire interface module), refer to the STM8 SWIM communication protocol and debug module user manual (UM0470).

For information on the STM8 core, refer to the STM8 CPU programming manual (PM0044).

Low density value line devices provide the following benefits:

- Integrated system
 - 8 Kbytes of low-density embedded Flash program memory
 - 256 bytes of data EEPROM
 - 1 Kbyte of RAM
 - Internal high-speed and low-power low speed RC
 - Embedded reset
- Ultra low power consumption
 - 1 μ A in Active-halt mode
 - Clock gated system and optimized power management
 - Capability to execute from RAM for Low power wait mode and Low power run mode
- Advanced features
 - Up to 16 MIPS at 16 MHz CPU clock frequency
 - Direct memory access (DMA) for memory-to-memory or peripheral-to-memory access
- Short development cycles
 - Application scalability across a common family product architecture with compatible pinout, memory map and modular peripherals
 - Wide choice of development tools

These features make the value line STM8L05xxx ultra low power microcontroller family suitable for a wide range of consumer and mass market applications.

Refer to [Table 1: Low density value line STM8L05xxx low power device features and peripheral counts](#) and [Section 3: Functional overview](#) for an overview of the complete range of peripherals proposed in this family.

[Figure 1](#) shows the block diagram of the low density value line STM8L05xxx family.

2 Description

The low density value line STM8L05xxx devices are members of the STM8L ultra low power 8-bit family.

The value line STM8L05xxx ultra low power family features an enhanced STM8 CPU core providing increased processing power (up to 16 MIPS at 16 MHz) while maintaining the advantages of a CISC architecture with improved code density, a 24-bit linear addressing space and an optimized architecture for low power operations.

The family includes an integrated debug module with a hardware interface (SWIM) which allows non-intrusive In-Application debugging and ultra-fast Flash programming.

Low density value line STM8L05xxx microcontrollers feature embedded data EEPROM and low power, low-voltage, single-supply program Flash memory.

The devices incorporate an extensive range of enhanced I/Os and peripherals, a 12-bit ADC, a real-time clock, two 16-bit timers, one 8-bit timer, as well as standard communication interfaces such as an SPI, an I²C interface, and one USART.

The modular design of the peripheral set allows the same peripherals to be found in different ST microcontroller families including 32-bit families. This makes any transition to a different family very easy, and simplified even more by the use of a common set of development tools.

All value line STM8L ultra low power products are based on the same architecture with the same memory mapping and a coherent pinout.

2.1 Device overview

Table 1. Low density value line STM8L05xxx low power device features and peripheral counts

Features		STM8L051F3
Flash (Kbytes)		8
Data EEPROM (Bytes)		256
RAM (Kbytes)		1
Timers	Basic	1 (8-bit)
	General purpose	2 (16-bit)
Communication interfaces	SPI	1
	I2C	1
	USART	1
GPIOs		18 ⁽¹⁾
12-bit synchronized ADC (number of channels)		1 (10)
Others		RTC, window watchdog, independent watchdog, 16-MHz and 32-kHz internal RC, 1- to 16-MHz and 32-kHz external oscillator
CPU frequency		16 MHz
Operating voltage		1.8 to 3.6 V
Operating temperature		-40 to +85 °C
Package		TSSOP20

1. The number of GPIOs given in this table includes the NRST/PA1 pin but the application can use the NRST/PA1 pin as general purpose output only (PA1).

2.2 Ultra low power continuum

The ultra low power value line STM8L05xxx and STM8L15xxx are fully pin-to-pin, software and feature compatible. Besides the full compatibility within the STM8L family, the devices are part of STMicroelectronics microcontrollers ultra low power strategy which also includes STM8L101xx and STM32L15xxx. The STM8L and STM32L families allow a continuum of performance, peripherals, system architecture, and features.

They are all based on STMicroelectronics 0.13 μm ultra-low leakage process.

- Note:*
- 1 The STM8L05xxx are pin-to-pin compatible with STM8L101xx devices.
 - 2 The STM32L family is pin-to-pin compatible with the general purpose STM32F family. Please refer to STM32L15x documentation for more information on these devices.

Performance

All families incorporate highly energy-efficient cores with both Harvard architecture and pipelined execution: advanced STM8 core for STM8L families and ARM[®] 32-bit Cortex[®]-M3 core for STM32L family. In addition specific care for the design architecture has been taken to optimize the mA/DMIPS and mA/MHz ratios.

This allows the ultra low power performance to range from 5 up to 33.3 DMIPs.

Shared peripherals

STM8L05xx, STM8L15xx and STM32L15xx share identical peripherals which ensure a very easy migration from one family to another:

- Analog peripheral: ADC1
- Digital peripherals: RTC and some communication interfaces

Common system strategy

To offer flexibility and optimize performance, the STM8L and STM32L devices use a common architecture:

- Same power supply range from 1.8 to 3.6 V
- Architecture optimized to reach ultra low consumption both in low power modes and Run mode
- Fast startup strategy from low power modes
- Flexible system clock
- Ultra-safe reset: same reset strategy for both STM8L and STM32L including power-on reset, power-down reset, brownout reset and programmable voltage detector.

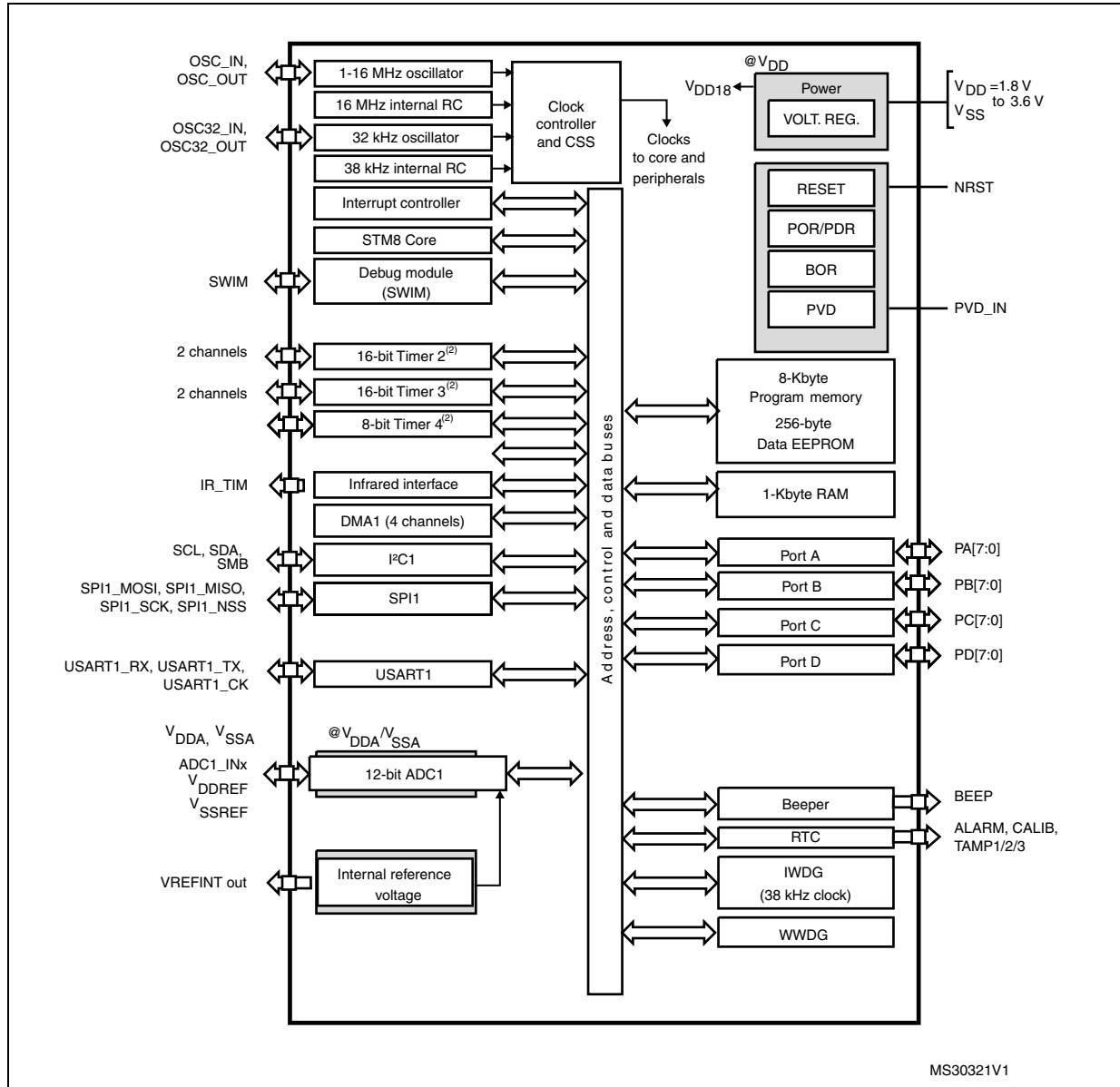
Features

ST ultra low power continuum also lies in feature compatibility:

- More than 10 packages with pin count from 20 to 100 pins and size down to 3 x 3 mm
- Memory density ranging from 4 to 128 Kbytes

3 Functional overview

Figure 1. Low density value line STM8L05xxx device block diagram



- Legend:**
 ADC: Analog-to-digital converter
 BOR: Brownout reset
 DMA: Direct memory access
 I²C: Inter-integrated circuit multimaster interface
 IWDG: Independent watchdog
 POR/PDR: Power-on reset / power-down reset
 RTC: Real-time clock
 SPI: Serial peripheral interface
 SWIM: Single wire interface module
 USART: Universal synchronous asynchronous receiver transmitter
 WWDG: Window watchdog

3.1 Low power modes

The low density value line STM8L05xxx devices support five low power modes to achieve the best compromise between low power consumption, short startup time and available wakeup sources:

- **Wait mode:** The CPU clock is stopped, but selected peripherals keep running. An internal or external interrupt or a Reset can be used to exit the microcontroller from Wait mode (WFE or WFI mode).
- **Low power run mode:** The CPU and the selected peripherals are running. Execution is done from RAM with a low speed oscillator (LSI or LSE). Flash memory and data EEPROM are stopped and the voltage regulator is configured in ultra low power mode. The microcontroller enters Low power run mode by software and can exit from this mode by software or by a reset.
All interrupts must be masked. They cannot be used to exit the microcontroller from this mode.
- **Low power wait mode:** This mode is entered when executing a Wait for event in Low power run mode. It is similar to Low power run mode except that the CPU clock is stopped. The wakeup from this mode is triggered by a Reset or by an internal or external event (peripheral event generated by the timers, serial interfaces, DMA controller (DMA1) and I/O ports). When the wakeup is triggered by an event, the system goes back to Low power run mode.
All interrupts must be masked. They cannot be used to exit the microcontroller from this mode.
- **Active-halt mode:** CPU and peripheral clocks are stopped, except RTC. The wakeup can be triggered by RTC interrupts, external interrupts or reset.
- **Halt mode:** CPU and peripheral clocks are stopped, the device remains powered on. The RAM content is preserved. The wakeup is triggered by an external interrupt or reset. A few peripherals have also a wakeup from Halt capability. Switching off the internal reference voltage reduces power consumption. Through software configuration it is also possible to wake up the device without waiting for the internal reference voltage wakeup time to have a fast wakeup time of 5 μ s.

3.2 Central processing unit STM8

3.2.1 Advanced STM8 Core

The 8-bit STM8 core is designed for code efficiency and performance with an Harvard architecture and a 3-stage pipeline.

It contains 6 internal registers which are directly addressable in each execution context, 20 addressing modes including indexed indirect and relative addressing, and 80 instructions.

Architecture and registers

- Harvard architecture
- 3-stage pipeline
- 32-bit wide program memory bus - single cycle fetching most instructions
- X and Y 16-bit index registers - enabling indexed addressing modes with or without offset and read-modify-write type data manipulations
- 8-bit accumulator
- 24-bit program counter - 16-Mbyte linear memory space
- 16-bit stack pointer - access to a 64-Kbyte level stack
- 8-bit condition code register - 7 condition flags for the result of the last instruction

Addressing

- 20 addressing modes
- Indexed indirect addressing mode for lookup tables located anywhere in the address space
- Stack pointer relative addressing mode for local variables and parameter passing

Instruction set

- 80 instructions with 2-byte average instruction size
- Standard data movement and logic/arithmetic functions
- 8-bit by 8-bit multiplication
- 16-bit by 8-bit and 16-bit by 16-bit division
- Bit manipulation
- Data transfer between stack and accumulator (push/pop) with direct stack access
- Data transfer using the X and Y registers or direct memory-to-memory transfers

3.2.2 Interrupt controller

The low density value line STM8L05xxx features a nested vectored interrupt controller:

- Nested interrupts with 3 software priority levels
- 32 interrupt vectors with hardware priority
- Up to 17 external interrupt sources on 11 vectors
- Trap and reset interrupts

3.3 Reset and supply management

3.3.1 Power supply scheme

The device requires a 1.8 V to 3.6 V operating supply voltage (V_{DD}). The external power supply pins must be connected as follows:

- V_{SS1} ; V_{DD1} = 1.8 to 3.6 V: external power supply for I/Os and for the internal regulator. Provided externally through V_{DD1} pins, the corresponding ground pin is V_{SS1} .
- V_{SSA} ; V_{DDA} = 1.8 to 3.6 V: external power supplies for analog peripherals. V_{DDA} and V_{SSA} must be connected to V_{DD1} and V_{SS1} , respectively.
- V_{SS2} ; V_{DD2} = 1.8 to 3.6 V: external power supplies for I/Os. V_{DD2} and V_{SS2} must be connected to V_{DD1} and V_{SS1} , respectively.
- V_{REF+} , V_{REF-} (for ADC1): external reference voltage for ADC1. Must be provided externally through V_{REF+} and V_{REF-} pin.

3.3.2 Power supply supervisor

The device has an integrated ZEROPOWER power-on reset (POR)/power-down reset (PDR), coupled with a brownout reset (BOR) circuitry. When the microcontroller operates between 1.8 and 3.6 V, BOR is always active and ensures proper operation starting from 1.8 V. After the 1.8 V BOR threshold is reached, the option byte loading process starts, either to confirm or modify default thresholds, or to disable BOR permanently.

Five BOR thresholds are available through option bytes, starting from 1.8 V to 3 V. To reduce the power consumption in Halt mode, it is possible to automatically switch off the internal reference voltage (and consequently the BOR) in Halt mode. The device remains in reset state when V_{DD} is below a specified threshold, $V_{POR/PDR}$ or V_{BOR} , without the need for any external reset circuit.

The device features an embedded programmable voltage detector (PVD) that monitors the V_{DD}/V_{DDA} power supply and compares it to the V_{PVD} threshold. This PVD offers 7 different levels between 1.85 V and 3.05 V, chosen by software, with a step around 200 mV. An interrupt can be generated when V_{DD}/V_{DDA} drops below the V_{PVD} threshold and/or when V_{DD}/V_{DDA} is higher than the V_{PVD} threshold. The interrupt service routine can then generate a warning message and/or put the MCU into a safe state. The PVD is enabled by software.

3.3.3 Voltage regulator

The low density value line STM8L05xxx embeds an internal voltage regulator for generating the 1.8 V power supply for the core and peripherals.

This regulator has two different modes:

- Main voltage regulator mode (MVR) for Run, Wait for interrupt (WFI) and Wait for event (WFE) modes.
- Low power voltage regulator mode (LPVR) for Halt, Active-halt, Low power run and Low power wait modes.

When entering Halt or Active-halt modes, the system automatically switches from the MVR to the LPVR in order to reduce current consumption.

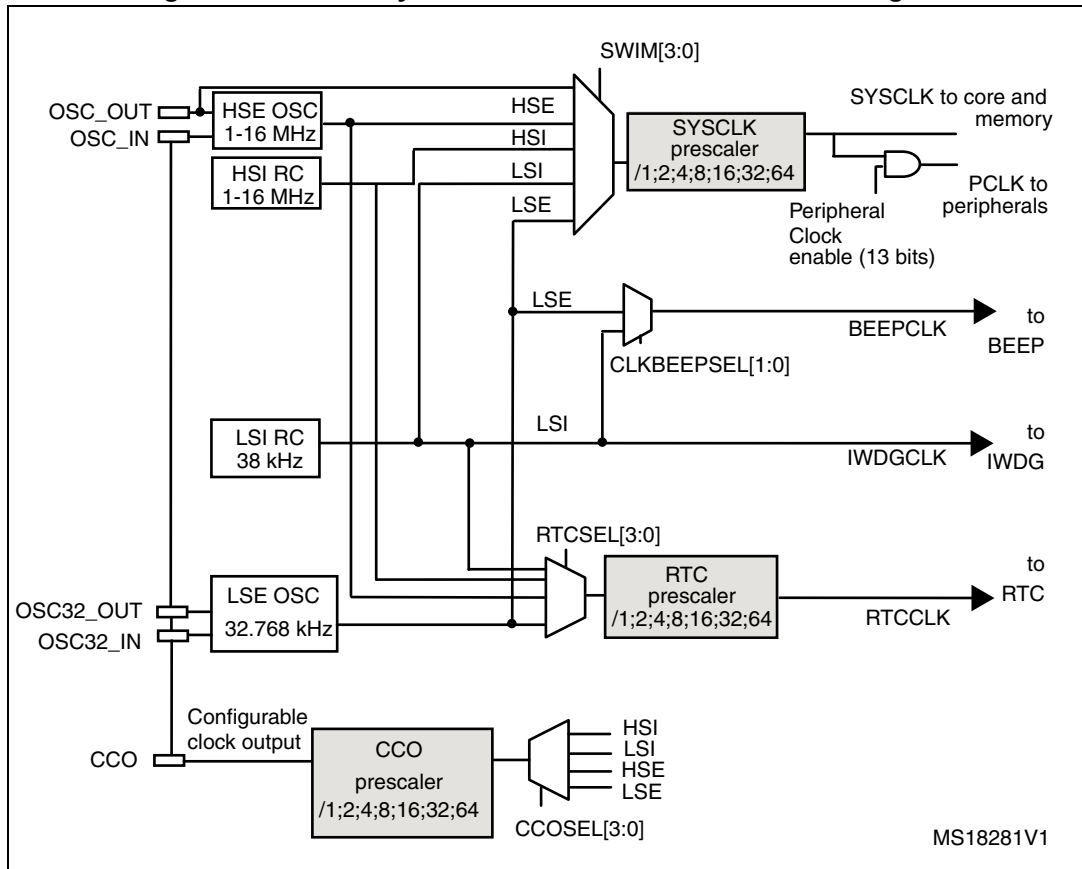
3.4 Clock management

The clock controller distributes the system clock (SYSCLK) coming from different oscillators to the core and the peripherals. It also manages clock gating for low power modes and ensures clock robustness.

Features

- **Clock prescaler:** to get the best compromise between speed and current consumption the clock frequency to the CPU and peripherals can be adjusted by a programmable prescaler.
- **Safe clock switching:** Clock sources can be changed safely on the fly in run mode through a configuration register.
- **Clock management:** To reduce power consumption, the clock controller can stop the clock to the core, individual peripherals or memory.
- **System clock sources:** four different clock sources can be used to drive the system clock:
 - 1-16 MHz High speed external crystal (HSE)
 - 16 MHz High speed internal RC oscillator (HSI)
 - 32.768 Low speed external crystal (LSE)
 - 38 kHz Low speed internal RC (LSI)
- **RTC clock sources:** the above four sources can be chosen to clock the RTC whatever the system clock.
- **Startup clock:** After reset, the microcontroller restarts by default with an internal 2 MHz clock (HSI/8). The prescaler ratio and clock source can be changed by the application program as soon as the code execution starts.
- **Clock security system (CSS):** This feature can be enabled by software. If a HSE clock failure occurs, it is automatically switched to HSI.
- **Configurable main clock output (CCO):** This outputs an external clock for use by the application.

Figure 2. Low density value line STM8L05xxx clock tree diagram



1. The HSE clock source can be either an external crystal/ceramic resonator or an external source (HSE bypass). Refer to Section HSE clock in the STM8L15x and STM8L16x reference manual (RM0031).
2. The LSE clock source can be either an external crystal/ceramic resonator or a external source (LSE bypass). Refer to Section LSE clock in the STM8L15x and STM8L16x reference manual (RM0031).

3.5 Low power real-time clock

The real-time clock (RTC) is an independent binary coded decimal (BCD) timer/counter.

Six byte locations contain the second, minute, hour (12/24 hour), week day, date, month, year, in BCD (binary coded decimal) format. Correction for 28, 29 (leap year), 30, and 31 day months are made automatically.

It provides a programmable alarm and programmable periodic interrupts with wakeup from Halt capability.

- Periodic wakeup time using the 32.768 kHz LSE with the lowest resolution (of 61 μ s) is from min. 122 μ s to max. 3.9 s. With a different resolution, the wakeup time can reach 36 hours
- Periodic alarms based on the calendar can also be generated from every second to every year

3.6 Memories

The low density value line STM8L05xxx devices have the following main features:

- Up to 1 Kbyte of RAM
- The non-volatile memory is divided into three arrays:
 - 8 Kbytes of low-density embedded Flash program memory
 - 256 bytes of Data EEPROM
 - Option bytes

The EEPROM embeds the error correction code (ECC) feature.

The option byte protects part of the Flash program memory from write and readout piracy.

3.7 DMA

A 4-channel direct memory access controller (DMA1) offers a memory-to-memory and peripherals-from/to-memory transfer capability. The 4 channels are shared between the following IPs with DMA capability: ADC1, I2C1, SPI1, USART1, and the three timers.

3.8 Analog-to-digital converter

- 12-bit analog-to-digital converter (ADC1) with 10 channels (including 1 fast channel) and internal reference voltage
- Conversion time down to 1 μ s with $f_{\text{SYSCLK}} = 16$ MHz
- Programmable resolution
- Programmable sampling time
- Single and continuous mode of conversion
- Scan capability: automatic conversion performed on a selected group of analog inputs
- Analog watchdog
- Triggered by timer

Note: ADC1 can be served by DMA1.

3.9 System configuration controller and routing interface

The system configuration controller provides the capability to remap some alternate functions on different I/O ports. TIM4 and ADC1 DMA channels can also be remapped.

The highly flexible routing interface controls the routing of internal analog signals to ADC1 and the internal reference voltage V_{REFINT} .

3.10 Timers

Low density value line STM8L05xxx devices contain two 16-bit general purpose timers (TIM2 and TIM3) and one 8-bit basic timer (TIM4).

All the timers can be served by DMA1.

[Table 2](#) compares the features of the advanced control, general-purpose and basic timers.

Table 2. Timer feature comparison

Timer	Counter resolution	Counter type	Prescaler factor	DMA1 request generation	Capture/compare channels	Complementary outputs
TIM2	16-bit	up/down	Any power of 2 from 1 to 128	Yes	2	None
TIM3					0	
TIM4	8-bit	up	Any power of 2 from 1 to 32768			

3.10.1 16-bit general purpose timers (TIM2, TIM3)

- 16-bit autoreload (AR) up/down-counter
- 7-bit prescaler adjustable to fixed power of 2 ratios (1...128)
- 2 individually configurable capture/compare channels
- PWM mode
- Interrupt capability on various events (capture, compare, overflow, break, trigger)
- Synchronization with other timers or external signals (external clock, reset, trigger and enable)

3.10.2 8-bit basic timer (TIM4)

The 8-bit timer consists of an 8-bit up auto-reload counter driven by a programmable prescaler. It can be used for timebase generation with interrupt generation on timer overflow.

3.11 Watchdog timers

The watchdog system is based on two independent timers providing maximum security to the applications.

3.11.1 Window watchdog timer

The window watchdog (WWDG) is used to detect the occurrence of a software fault, usually generated by external interferences or by unexpected logical conditions, which cause the application program to abandon its normal sequence.

3.11.2 Independent watchdog timer

The independent watchdog peripheral (IWDG) can be used to resolve processor malfunctions due to hardware or software failures.

It is clocked by the internal LSI RC clock source, and thus stays active even in case of a CPU clock failure.

3.12 Beeper

The beeper function outputs a signal on the BEEP pin for sound generation. The signal is in the range of 1, 2 or 4 kHz.

3.13 Communication interfaces

3.13.1 SPI

The serial peripheral interfaces (SPI1) provide half/ full duplex synchronous serial communication with external devices.

- Maximum speed: 8 Mbit/s ($f_{\text{SYSCLK}}/2$) both for master and slave
- Full duplex synchronous transfers
- Simplex synchronous transfers on 2 lines with a possible bidirectional data line
- Master or slave operation - selectable by hardware or software
- Hardware CRC calculation
- Slave/master selection input pin

Note: SPI1 can be served by the DMA1 Controller.

3.13.2 I²C

The I²C bus interface (I2C1) provides multi-master capability, and controls all I²C bus-specific sequencing, protocol, arbitration and timing.

- Master, slave and multi-master capability
- Standard mode up to 100 kHz and fast speed modes up to 400 kHz
- 7-bit and 10-bit addressing modes
- SMBus 2.0 and PMBus support
- Hardware CRC calculation

Note: I²C1 can be served by the DMA1 Controller.

3.13.3 USART

The USART interface (USART1) allows full duplex, asynchronous communications with external devices requiring an industry standard NRZ asynchronous serial data format. It offers a very wide range of baud rates.

- 1 Mbit/s full duplex SCI
- SPI1 emulation
- High precision baud rate generator
- Smartcard emulation
- IrDA SIR encoder decoder
- Single wire half duplex mode

Note: USART1 can be served by the DMA1 Controller.

3.14 Infrared (IR) interface

The low density STM8L05xxx devices contain an infrared interface which can be used with an IR LED for remote control functions. Two timer output compare channels are used to generate the infrared remote control signals.

3.15 Development support

Development tools

Development tools for the STM8 microcontrollers include:

- The STice emulation system offering tracing and code profiling
- The STVD high-level language debugger including C compiler, assembler and integrated development environment
- The STVP Flash programming software

The STM8 also comes with starter kits, evaluation boards and low-cost in-circuit debugging/programming tools.

Single wire data interface (SWIM) and debug module

The debug module with its single wire data interface (SWIM) permits non-intrusive real-time in-circuit debugging and fast memory programming.

The Single wire interface is used for direct access to the debugging module and memory programming. The interface can be activated in all device operation modes.

The non-intrusive debugging module features a performance close to a full-featured emulator. Beside memory and peripherals, CPU operation can also be monitored in real-time by means of shadow registers.

Bootloader

The low density value line STM8L05xxx ultra low power devices feature a built-in bootloader (see *UM0560: STM8 bootloader user manual*).

The bootloader is used to download application software into the device memories, including RAM, program and data memory, using standard serial interfaces. It is a complementary solution to programming via the SWIM debugging interface.

4 Pin description

Figure 3. STM8L051F3 20-pin TSSOP20 package pinout

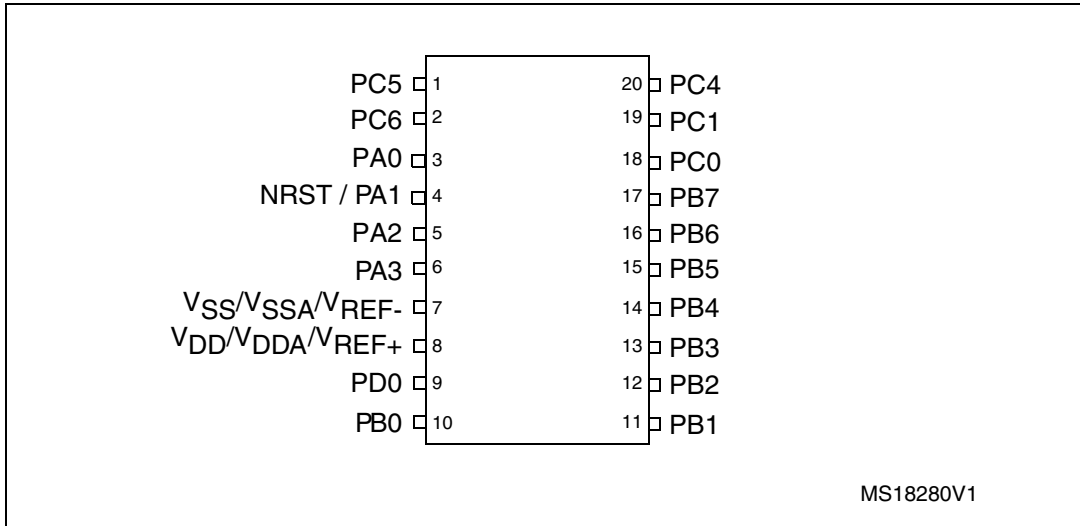


Table 3. Legend/abbreviation for [Table 4](#)

Type	I= input, O = output, S = power supply	
Level	Output	HS = high sink/source (20 mA)
	Input	FT - five volt tolerant
Port and control configuration	Input	float = floating, wpu = weak pull-up
	Output	T = true open drain, OD = open drain, PP = push pull
Reset state	Bold X (pin state after reset release). Unless otherwise specified, the pin state is the same during the reset phase (i.e. "under reset") and after internal reset release (i.e. at reset state).	

Table 4. Low density value line STM8L05xxx pin description

pin n°	Pin name	Type	I/O level	Input			Output			Main function (after reset)	Default alternate function
				floating	wpu	Ext. interrupt	High sink/source	OD	PP		
4	NRST/PA1 ⁽¹⁾	I/O		X			HS		X	Reset	PA1
5	PA2/OSC_IN/[USART_TX] ⁽²⁾ / [SPI_MISO] ⁽²⁾	I/O		X	X	X	HS	X	X	Port A2	HSE oscillator input / [USART transmit] / [SPI master in- slave out]
6	PA3/OSC_OUT/[USART_RX] ⁽²⁾ / [SPI_MOSI] ⁽²⁾	I/O		X	X	X	HS	X	X	Port A3	HSE oscillator output / [USART receive] / [SPI master out/slave in]
10	PB0 ⁽³⁾ /TIM2_CH1/ADC1_IN18	I/O		X	X	X	HS	X	X	Port B0	Timer 2 - channel 1 / ADC1_IN18
11	PB1/TIM3_CH1/ADC1_IN17	I/O		X	X	X	HS	X	X	Port B1	Timer 3 - channel 1 / ADC1_IN17
12	PB2/TIM2_CH2/ADC1_IN16	I/O		X	X	X	HS	X	X	Port B2	Timer 2 - channel 2 ADC1_IN16
13	PB3/TIM2_ETR/ ADC1_IN15/RTC_ALARM	I/O		X	X	X	HS	X	X	Port B3	Timer 2 - external trigger / ADC1_IN15 / RTC_ALARM
14	PB4 ⁽³⁾ /SPI1_NSS/ADC1_IN14	I/O		X	X	X	HS	X	X	Port B4	SPI master/slave select / ADC1_IN14
15	PB5/SPI_SCK/ /ADC1_IN13	I/O		X	X	X	HS	X	X	Port B5	[SPI clock] / ADC1_IN13
16	PB6/SPI1_MOSI/ ADC1_IN12	I/O		X	X	X	HS	X	X	Port B6	SPI master out/ slave in / ADC1_IN12
17	PB7/SPI1_MISO/ADC1_IN11	I/O		X	X	X	HS	X	X	Port B7	SPI1 master in- slave out/ ADC1_IN11
18	PC0/I2C_SDA	I/O	FT	X		X			T ⁽⁴⁾	Port C0	I2C data
19	PC1/I2C_SCL	I/O	FT	X		X			T ⁽³⁾	Port C1	I2C clock
20	PC4/USART_CK/ I2C_SMB/CCO/ADC1_IN4	I/O		X	X	X	HS	X	X	Port C4	USART synchronous clock / I2C1_SMB / Configurable clock output / ADC1_IN4
1	PC5/OSC32_IN / [SPI1_NSS] ⁽²⁾ / [USART_TX]/TIM2_CH1	I/O		X	X	X	HS	X	X	Port C5	LSE oscillator input / [SPI master/slave select] / [USART transmit]/Timer 2 -channel 1

Table 4. Low density value line STM8L05xxx pin description (continued)

pin n°	Pin name	Type	I/O level	Input			Output			Main function (after reset)	Default alternate function
				floating	wpu	Ext. interrupt	High sink/source	OD	PP		
2	PC6/OSC32_OUT/[SPI_SCK] ⁽²⁾ / [USART_RX]/TIM2_CH2	I/O		X	X	X	HS	X	X	Port C6	LSE oscillator output / [SPI clock] / [USART receive] / Timer 2 - channel 2
9	PD0/TIM3_CH2/[ADC1_TRIG] ⁽²⁾ / ADC1_IN22	I/O		X	X	X	HS	X	X	Port D0	Timer 3 - channel 2 / [ADC1_Trigger] / ADC1_IN22
8	V _{DD} / V _{DDA} / V _{REF+}	S									Digital supply voltage / ADC1 positive voltage reference
7	V _{SS} / V _{REF-} / V _{SSA}										Ground voltage / ADC1 negative voltage reference / Analog ground voltage
3	PA0 ⁽⁵⁾ / [USART_CK] ⁽²⁾ / SWIM/BEEP/IR_TIM ⁽⁶⁾	I/O		X	X	X	HS ⁽⁶⁾	X	X	Port A0	[USART1 synchronous clock] ⁽²⁾ / SWIM input and output / Beep output / Infrared Timer output

- At power-up, the PA1/NRST pin is a reset input pin with pull-up. To be used as a general purpose pin (PA1), it can be configured only as output open-drain or push-pull, not as a general purpose input. Refer to Section *Configuring NRST/PA1 pin as general purpose output* in the STM8L15xxx and STM8L16xxx reference manual (RM0031).
- [] Alternate function remapping option (if the same alternate function is shown twice, it indicates an exclusive choice not a duplication of the function).
- A pull-up is applied to PB0 and PB4 during the reset phase. These two pins are input floating after reset release.
- In the open-drain output column, 'T' defines a true open-drain I/O (P-buffer and protection diode to V_{DD} are not implemented).
- The PA0 pin is in input pull-up during the reset phase and after reset release.
- High Sink LED driver capability available on PA0.

Note: The slope control of all GPIO pins, except true open drain pins, can be programmed. By default, the slope control is limited to 2 MHz.

4.1 System configuration options

As shown in [Table 4: Low density value line STM8L05xxx pin description](#), some alternate functions can be remapped on different I/O ports by programming one of the two remapping registers described in the "Routing interface (RI) and system configuration controller" section in the STM8L15xx and STM8L16xx reference manual (RM0031).